

# SL22 thru SL24

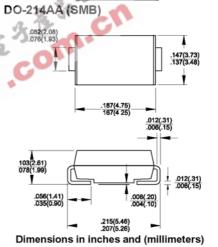
#### **Features**

- ◆ For surface mounted application
- ◆ Metal silicon junction, majority carrier conduction
- Low forward voltage drop
- ◆ Easy pick and place
- ◆ High surge current capability
- Plastic material used carries Underwriters Laboratory Classification 94V-O
- ◆ Epitaxial construction
- High temperature soldering: 250°C / 10 seconds at terminals

#### **Mechanical Data**

- ◆ Cases: Molded plastic
- ◆ Terminals: Solder plated
- ◆ Polarity: Indicated by cathode band
- ◆ Weight: 0.003 ounce, 0.093 gram





## **Maximum Ratings and Electrical Characteristics**

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%

Parameter	Symbols	SL22	SL23	SL24	Units
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	20	30	40	Volts
Maximum RMS voltage	V <sub>RMS</sub>	14	21	28	Volts
Maximum DC blocking voltage	V <sub>DC</sub>	20	30	40	Volts
Maximum average forward rectified current See Fig. 1	I <sub>(AV)</sub>	2.0			Amps
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	50.0			Amps
Maximum instantaneous forward voltage @ 2.0A (Note 1)	V <sub>F</sub>	0.385	0.385	0.400	Volts
Maximum DC reverse current @ T <sub>x</sub> =25°C at rated DC blocking voltage @ T <sub>A</sub> =100°C	I <sub>R</sub>	3.0 150			mA
Maximum thermal resistance (Note 2)	R <sub>eJL</sub> R <sub>eJA</sub>	25 75			°C/W
Operating junction temperature range	T <sub>J</sub>	-55 to +125			°C
Storage temperature range	T <sub>STG</sub>	-55 to +150			°C

Notes:

- 1. Pulse Test with PW=300 usec, 1% Duty Cycle.
- 2. Measured on P.C. Board with 0.2 x 0.2" (5.0 x 5.0 mm) Copper Pad Areas.

### **RATINGS AND CHARACTERISTIC CURVES**

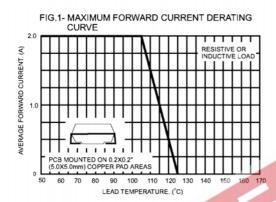


FIG.3- TYPICAL FORWARD CHARACTERISTICS

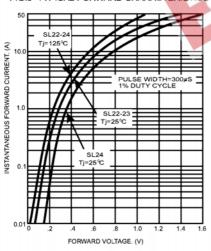
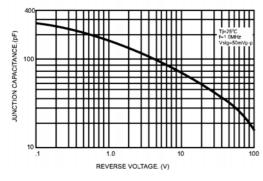


FIG.5- TYPICAL JUNCTION CAPACITANCE



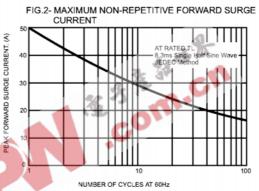


FIG.4- TYPICAL REVERSE CHARACTERISTICS

